

taoglas

DSGP. 18.2.A

### DSGP.1575.18.2.A.02

### **Description:**

#### Features:

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## 1. Introduction



The DSGP.1575.18.2.A.02 is a ceramic GPS L1 / GALILEO E1 passive patch antenna, 18mm square, with a low profile of 2mm thickness. It is designed for applications in space constrained navigation devices, vehicle tracking/fleet management systems, as well as telematics devices.

The antenna has been tuned on a 50 x 50 mm ground plane, working at 1575.42MHz with a 2.4 dBi gain. The ceramic patch is mounted via SMT process, ideal for high volume low cost assembly. It is manufactured and tested in a TS16949 first tier automotive approved facility.

For further optimization to customer specific device environments where ground-plane size is different, custom tuned patch antennas can be supplied. For more details please contact your regional Taoglas sales office.



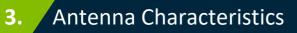
# 2. Specifications

GNSS Frequency Bands Covered							
GPS/QZSS	L1 1575.42MHz	L2 1227.6MHz	L5 1176.45MHz	L6 1278.75MHz			
	$\checkmark$						
GLONASS	L5R 1176.45MHz	L3PT 1201.5MHz	L2PT 1246MHz	L1CR 1575.42MHz	L1PT 1602MHz		
Galileo	E5a 1176.45MHz	E5b 1201.5MHz	E4 1215MHz	E3 1256MHz	E6 1278.75MHz	E2 1561MHz	L1 1575.42MHz
BeiDou	B1 1561MHz	B2 1207.14MHz	B3 1268.52MHz				
Compass	E5B(B2)/ E6(B3) 1268.56MHz	E2(B1) 1561MHz					
SBAS	Omnistar 1542.5MHz	WAAS/EGN OS 1575.42MHz					
		$\checkmark$					

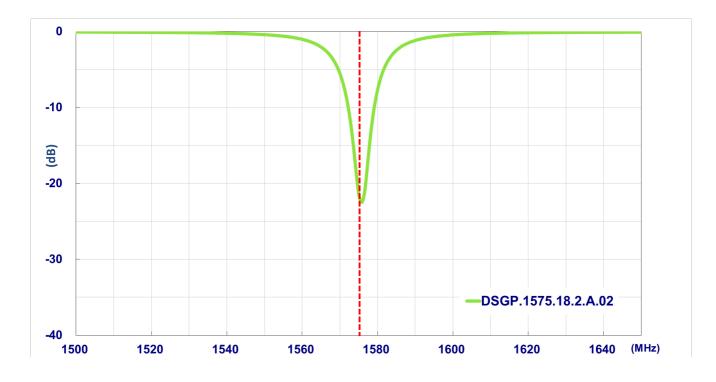


Electrical				
Frequency (MHz)	1575.42			
VSWR (max.)	2.0:1			
Passive Antenna Efficiency (%)	55.94			
Passive Antenna Gain at Zenith (dBi)	2.4			
Return Loss (dB)	<-10			
Impedance	50Ω			
Mechanical				
Height	255 ± 5 mm			
Base Diameter	16.05 ± 0.2 mm			
Whip Diameter	4 ± 0.2 mm			
Casing	ABS			
Connector	TNC Male			
	Environmental			
Temperature Range	Temperature Range-40°C to 85°C			
Humidity	Non-condensing 65°C 95% RH			
Moisture Sensitivity Level (MSL) 3 (168 Hours)				

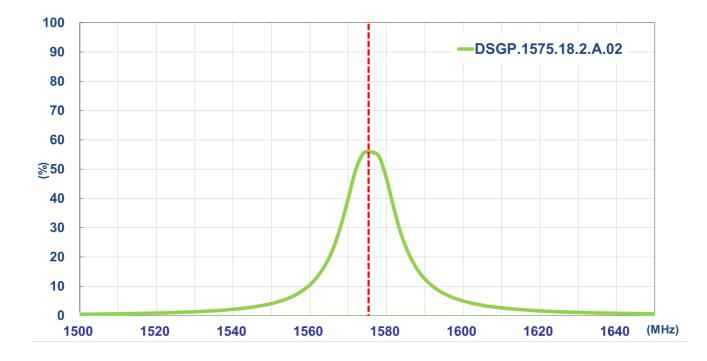




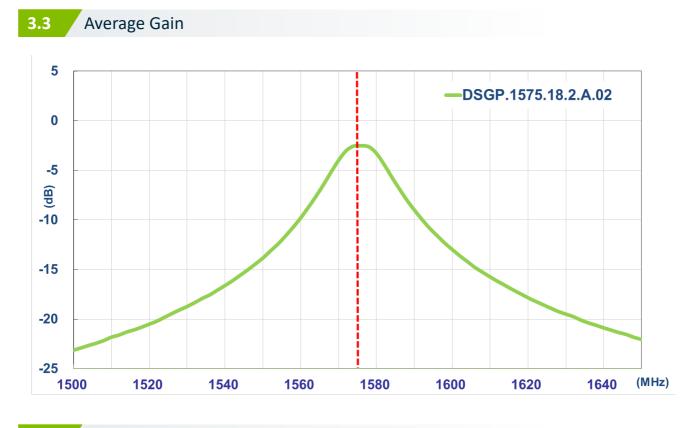
### 3.1 Return Loss



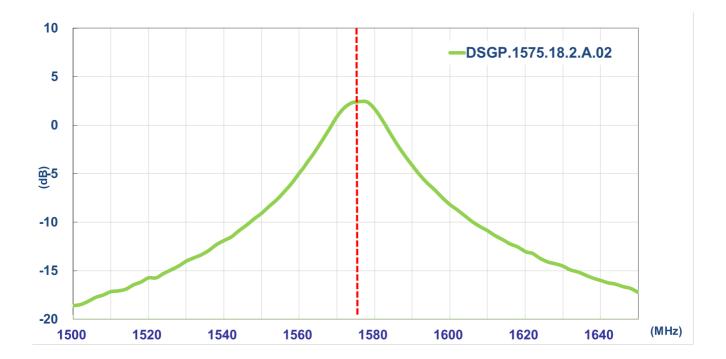
### **3.2** Efficiency













## 4. Radiation Patterns



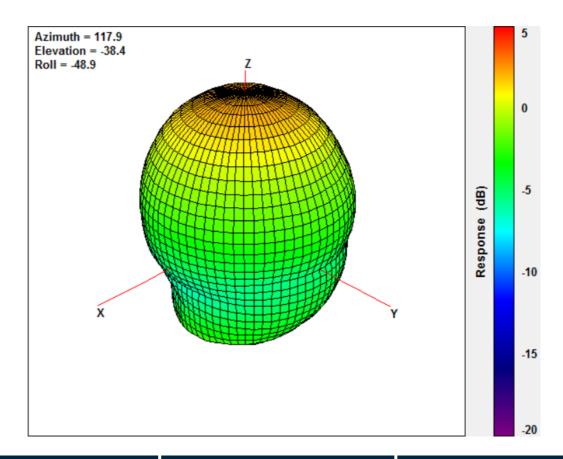


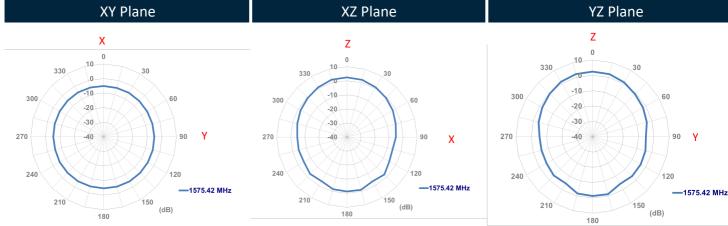
On Evaluation Board

Taoglas Part number: DSGPD.18B



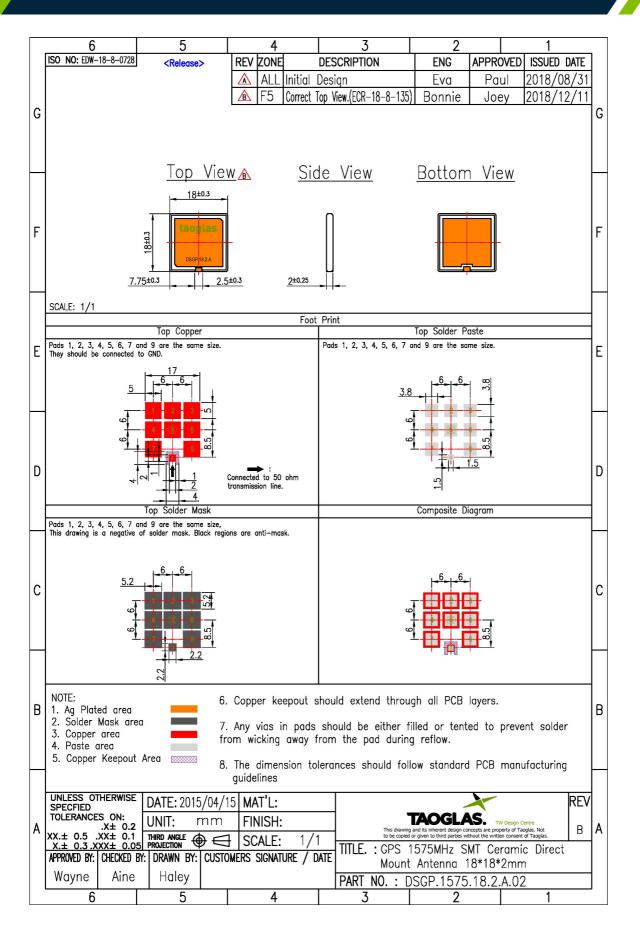
### 1575.42MHz 3D and 2D Radiation Patterns





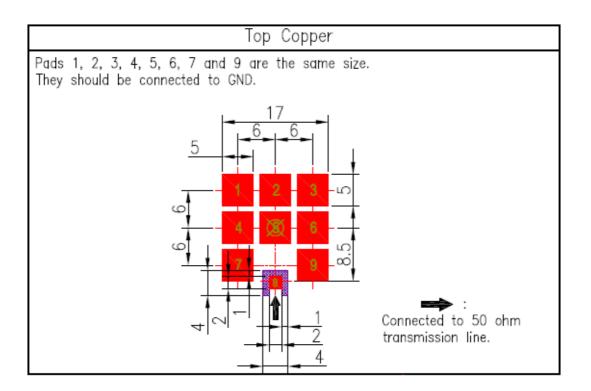


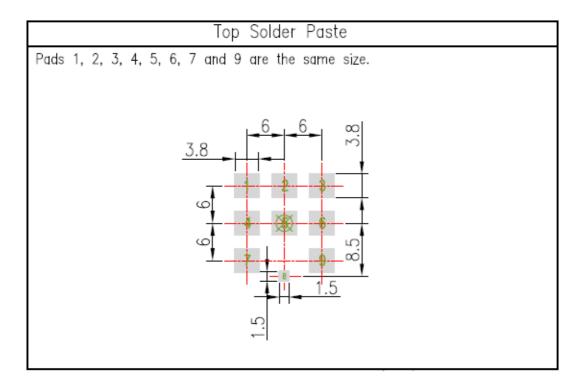




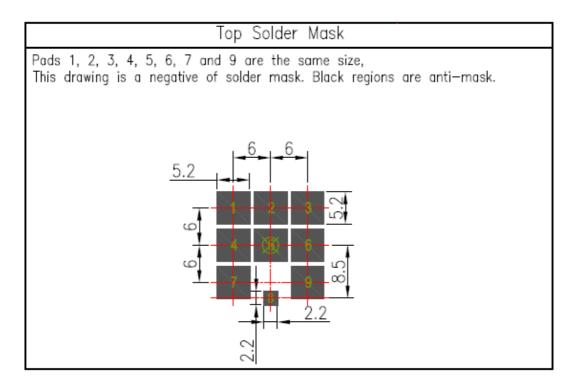


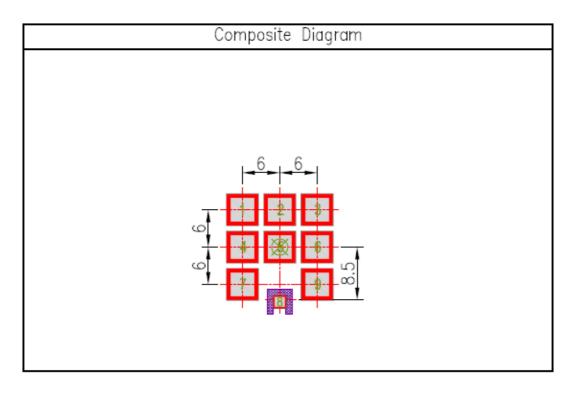
## Footprint











#### NOTE:

- 1. Ag Plated area
- 2. Solder Mask area
- 3. Copper area
- 4. Paste area
- 5. Copper Keepout Area

- 6. Copper keepout should extend through all PCB layers.
- 7. Any vias in pads should be either filled or tented to prevent solder from wicking away from the pad during reflow.
- 8. The dimension tolerances should follow standard PCB manufacturing guidelines

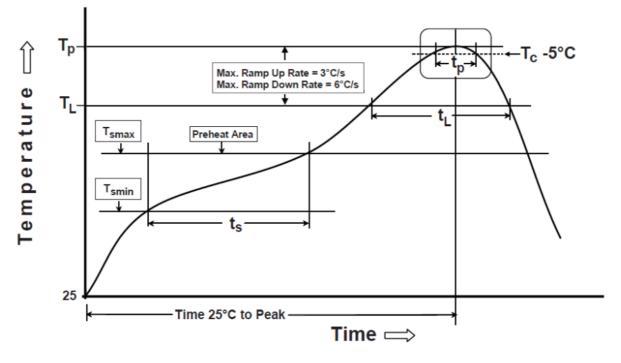


7.

# DSGP.1575.18 can be assembled following Pb-free assembly. According to the Standard IPC/JEDEC J-STD-020C, the temperature profile suggested is as follows:

Phase	Profile Features	Pb-Free Assembly (SnAgCu)
	Temperature Min (Tsmin)	150°C
PREHEAT	Temperature Max (Tsmax)	200°C
	Time(ts) from (Tsmin to Tsmax)	60-120 seconds
RAMP-UP	Avg. Ramp-up Rate (Tsmax to TP)	3°C/second(max)
REFLOW	Temperature (TL)	217°C
NEFLOW	Total Time above TL (tL)	30-100 seconds
PEAK	Temperature (TP)	260°C
PEAK	Time(tp)	2-5 seconds
RAMP-DOWN	Rate	3°C/second(max)
Time from 25°C to Peak Temperature		8 minutes max.
	Composition of solder paste	96.5Sn/3Ag/0.5Cu
	Solder Paste Model	SHENMAO PF606-P26

### The graphic shows temperature profile for component assembly process in reflow ovens



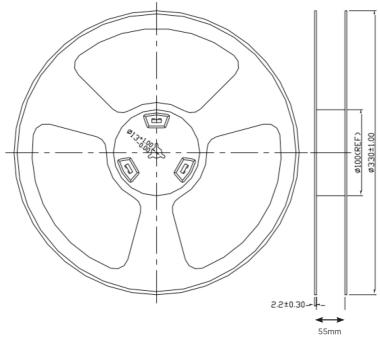
Soldering Iron condition : Soldering iron temperature 270°C±10°C.

Apply preheating at 120°C for 2-3 minutes. Finish soldering for each terminal within 3 seconds, if soldering iron temperature over270°C±10°C or 3 seconds, it will make cause component surface peeling or damage.

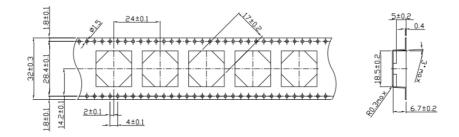


# Packaging

200 pc DSGP.1575.18.2.A.02 per reel Dimensions - Ø330\*55mm Weight - 800g



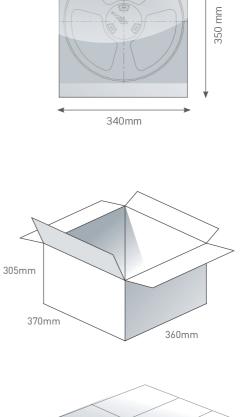




8.

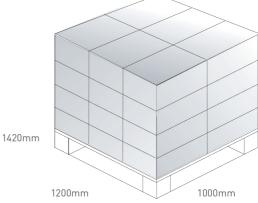


1 pc reel in small in Anti-static Bag Dimensions - 340\*350\*70mm Weight - 1.2Kg



4 Reels i n Anti-static Bags 800 pcs in one carton Carton Dimensions - 370\*360\*305mm Weight - 5.6Kg







Changelog for the datasheet

#### SPE-17-8-029 - DSGP.1575.18.2.A.02

Revision: C (Current Version)				
Date:	2021-09-07			
Changes:	Fixed Alignment of radiation patterns section. Added MSL rating. Fixed Font in tables.			
Changes Made by:	Erik Landi			

#### **Previous Revisions**

Revision: B		Revision: A (Origina	Revision: A (Original First Release)		
Date:	2019-09-17	Date:	2017-05-22		
Changes:	Updated Drawing	Notes:			
Changes Made by:	Jack Conroy	Author:	Jack Conroy		
enanges made by.					



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